

Data sheet acquired from Harris Semiconductor SCHS249A

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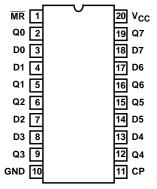
Octal D Flip-Flop with Reset

Features

- Buffered Inputs
- Typical Propagation Delay
 - 6.5ns at $V_{CC} = 5V$, $T_A = 25^{\circ}C$, $C_L = 50pF$
- Exceeds 2kV ESD Protection MIL-STD-883, Method 3015
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
- Balanced Propagation Delays
- AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
- ±24mA Output Drive Current
 - Fanout to 15 FAST™ ICs
 - Drives 50Ω Transmission Lines

Pinout

CD54AC273, CD54ACT273 (CDIP) CD74AC273, CD74ACT273 (PDIP, SOIC) TOP VIEW



Description

The 'AC273 and 'ACT273 devices are octal D-type flip-flops with reset that utilize advanced CMOS logic technology. Information at the D input is transferred to the Q output on the positive-going edge of the clock pulse. All eight flip-flops are controlled by a common clock (CP) and a common reset $(\overline{\mbox{MR}}).$ Resetting is accomplished by a low voltage level independent of the clock.

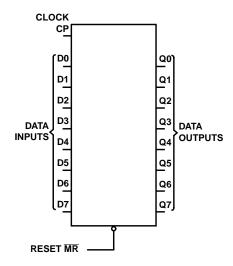
Ordering Information

PART NUMBER	TEMPERATURE RANGE	PACKAGE
CD74AC273E	-40°C to 85°C	20 Ld PDIP
CD54AC273F3A	-55 ⁰ C to 125 ⁰ C	20 Ld CDIP
CD74ACT273E	-40°C to 85°C	20 Ld PDIP
CD54ACT273F3A	-55 ⁰ C to 125 ⁰ C	20 Ld CDIP
CD74AC273M	-40°C to 85°C	20 Ld SOIC
CD74ACT273M	-40°C to 85°C	20 Ld SOIC

NOTES:

- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Wafer and die for this part number is available which meets all electrical specifications. Please contact your local sales office for ordering information.

Functional Diagram



TRUTH TABLE

	OUTPUTS		
RESET (MR)	CLOCK CP	DATA Dn	Qn
L	Х	Х	L
Н	↑	Н	Н
Н	1	L	L
Н	L	Х	Q0

Absolute Maximum Ratings

DC Supply Voltage, V _{CC} 0.5V to 6V
DC Input Diode Current, I _{IK}
For $V_1 < -0.5V$ or $V_1 > V_{CC} + 0.5V$ ±20mA
DC Output Diode Current, I _{OK}
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ ±50mA
DC V _{CC} or Ground Current, I _{CC or} I _{GND} (Note 3) ±100mA

Thermal Information

Thermal Resistance, θ_{JA} (Typical, Note 5)
E Package
M Package58°C/W
Maximum Junction Temperature (Plastic Package) 150°C
Maximum Storage Temperature Range65°C to 150°C
Maximum Lead Temperature (Soldering 10s)300°C

Operating Conditions

Temperature Range, T _A CD54AC273, CD54ACT27355°C to 125°C CD74AC273, CD74ACT27340°C to 85°C
Supply Voltage Range, V _{CC} (Note 4)
AC Types1.5V to 5.5V
ACT Types
DC Input or Output Voltage, V _I , V _O
Input Rise and Fall Slew Rate, dt/dv
AC Types, 1.5V to 3V 50ns (Max)
AC Types, 3.6V to 5.5V
ACT Types, 4.5V to 5.5V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

- 3. For up to 4 outputs per device, add $\pm 25 \text{mA}$ for each additional output.
- 4. Unless otherwise specified, all voltages are referenced to ground.
- 5. The package thermal impedance is calculated in accordance with JESD 51.

DC Electrical Specifications

		TEST CONDITIONS		Vcc	25	°c		С ТО °С		C TO 5°C	
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
AC TYPES					-						
High Level Input Voltage	V _{IH}	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	V _{IL}	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	V _{OH}	V _{IH} or V _{IL}	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V

DC Electrical Specifications (Continued)

	TEST CONDITIONS			v _{cc}	/cc 25°C		-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(v)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Low Level Output Voltage	V_{OL}	V _{IH} or V _{IL}	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	lį	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μА
Quiescent Supply Current MSI	I _{CC}	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μА
ACT TYPES											
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V _{OH}	V _{IH} or V _{IL}	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V _{OL}	V _{IH} or V _{IL}	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	lį	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μΑ
Quiescent Supply Current MSI	I _{CC}	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μΑ
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	Δl _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

NOTES:

- 6. Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
- 7. Test verifies a minimum 50Ω transmission-line-drive capability at $85^{o}C$, 75Ω at $125^{o}C$.

ACT Input Load Table

INPUT	UNIT LOAD
Dn	0.5
MR	0.57
СР	1

NOTE: Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at $25^{0}C.$

Prerequisite For Switching Function

			-40°C	ГО 85 ⁰ С	-55°C T		
PARAMETER	SYMBOL	V _{CC} (V)	MIN	MAX	MIN	MAX	UNITS
AC TYPES	•						
Data to CP Set-Up Time	t _{SU}	1.5	2	-	2	-	ns
		3.3 (Note 9)	2	-	2	-	ns
		5 (Note 10)	2	-	2	-	ns
Hold Time	t _H	1.5	2	-	2	-	ns
		3.3	2	-	2	-	ns
		5	2	-	2	-	ns
Removal Time, MR to CP	t _{REM}	1.5	2	-	2	-	ns
		3.3	2	-	2	-	ns
		5	2	-	2	-	ns
MR Pulse Width	t _W	1.5	55	-	63	-	ns
		3.3	6.1	-	7	-	ns
		5	4.4	-	5	-	ns
CP Pulse Width	t _W	1.5	55	-	63	-	ns
		3.3	6.1	-	7	-	ns
		5	4.4	-	5	-	ns
CP Frequency	f _{MAX}	1.5	9	-	8	-	MHz
		3.3	81	-	71	-	MHz
		5	114	-	100	-	MHz
ACT TYPES	•						
Data to CP Set-Up Time	t _{SU}	5 (Note 10)	2	-	2	-	ns
Hold Time	t _H	5	2	-	2	-	ns
Removal Time MR to CP	t _{REM}	5	2	-	2	-	ns
MR Pulse Width	t _W	5	4.4	-	5	-	ns
CP Pulse Width	t _W	5	5.3	-	6	-	ns
CP Frequency	f _{MAX}	5	97	-	85	-	MHz

Switching Specifications Input t_r , t_f = 3ns, C_L = 50pF (Worst Case)

			-40°	-40°C TO 85°C		-55°C TO 125°C			
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
AC TYPES	•								
Propagation Delay, CP to Qn	t _{PLH} , t _{PHL}	1.5	-	-	154	-	-	169	ns
		3.3 (Note 9)	4.9	-	17.2	4.7	-	18.9	ns
		5 (Note 10)	3.5	-	12.3	3.4	-	13.5	ns

Switching Specifications Input t_r , $t_f = 3ns$, $C_L = 50pF$ (Worst Case) (Continued)

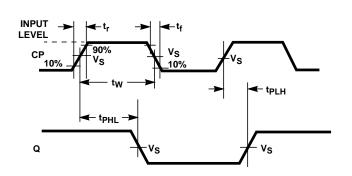
			-40°C TO 85°C		-55				
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Propagation Delay,	t _{PLH} , t _{PHL}	1.5	-	-	154	-	-	169	ns
MR to Qn		3.3	4.9	-	17.2	4.7	-	18.9	ns
		5	3.5	-	12.3	3.4	-	13.5	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 11)	-	-	45	-	-	45	-	pF
ACT TYPES									
Propagation Delay, CP to Qn	t _{PLH} , t _{PHL}	5 (Note 10)	3.5	-	12.3	3.4	-	13.5	ns
Propagation Delay, MR to Qn	t _{PLH} , t _{PHL}	5	3.5	-	12.3	3.4	-	13.5	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 11)	-	-	45	-	-	45	-	pF

NOTES:

- 8. Limits tested 100%.
- 9. 3.3V Min is at 3.6V, Max is at 3V.
- 10. 5V Min is at 5.5V, Max is at 4.5V.

11. C_{PD} is used to determine the dynamic power consumption per flip-flop. AC: $P_D = C_{PD} \ V_{CC}^2 f_i = \sum (C_L \ V_{CC}^2 f_o)$ ACT: $P_D = C_{PD} \ V_{CC}^2 f_i + \sum (C_L \ V_{CC}^2 f_o) + V_{CC} \ \Delta I_{CC}$ where f_i = input frequency, f_o = output frequency, C_L = output load capacitance, V_{CC} = supply voltage.

INPUT



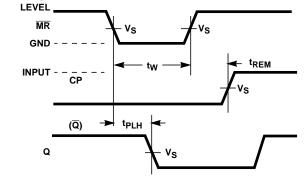


FIGURE 1. PROPAGATION DELAY TIMES AND CLOCK **PULSE WIDTH**

FIGURE 2. PREREQUISITE AND PROPAGATION DELAY TIMES FOR MASTER RESET

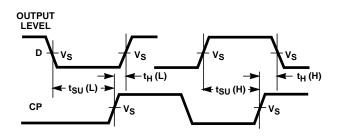
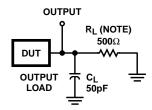


FIGURE 3. PREREQUISITE FOR CLOCK



NOTE: For AC Series Only: When $V_{\mbox{\footnotesize{CC}}}$ = 1.5V, R_L = 1k $\!\Omega.$

	AC	ACT
Input Level	V _{CC}	3V
Input Switching Voltage, V _S	0.5 V _{CC}	1.5V
Output Switching Voltage, V _S	0.5 V _{CC}	0.5 V _{CC}

FIGURE 4. PROPAGATION DELAY TIMES

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